

## 15MHz, BiMOS Operational Amplifier with MOSFET Input/CMOS Output

CA3130A and CA3130 are op amps that combine the advantage of both CMOS and bipolar transistors.

Gate-protected P-Channel MOSFET (PMOS) transistors are used in the input circuit to provide very-high-input impedance, very-low-input current, and exceptional speed performance. The use of PMOS transistors in the input stage results in common-mode input-voltage capability down to 0.5V below the negative-supply terminal, an important attribute in single-supply applications.

A CMOS transistor-pair, capable of swinging the output voltage to within 10mV of either supply-voltage terminal (at very high values of load impedance), is employed as the output circuit.

The CA3130 Series circuits operate at supply voltages ranging from 5V to 16V, ( $\pm 2.5V$  to  $\pm 8V$ ). They can be phase compensated with a single external capacitor, and have terminals for adjustment of offset voltage for applications requiring offset-null capability. Terminal provisions are also made to permit strobing of the output stage.

- The CA3130A offers superior input characteristics over those of the CA3130.

### Ordering Information

PART NO. (BRAND)	TEMP. RANGE (°C)	PACKAGE	PKG. DWG. #
CA3130AE	-55 to 125	8 Ld PDIP	E8.3
CA3130AM (3130A)	-55 to 125	8 Ld SOIC	M8.15
CA3130AM96 (3130A)	-55 to 125	8 Ld SOIC Tape and Reel	M8.15
CA3130AMZ (3130AZ) (Note)	-55 to 125	8 Ld SOIC (Pb-free)	M8.15
CA3130AMZ96 (3130AZ) (Note)	-55 to 125	8 Ld SOIC Tape and Reel (Pb-free)	M8.15
CA3130E	-55 to 125	8 Ld PDIP	E8.3
CA3130EZ (Note)	-55 to 125	8 Ld PDIP* (Pb-free)	E8.3
CA3130M (3130)	-55 to 125	8 Ld SOIC	M8.15
CA3130M96 (3130)	-55 to 125	8 Ld SOIC Tape and Reel	M8.15
CA3130MZ (3130MZ) (Note)	-55 to 125	8 Ld SOIC (Pb-free)	M8.15
CA3130MZ96 (3130MZ)	-55 to 125	8 Ld SOIC Tape and Reel (Pb-free)	M8.15

\*Pb-free PDIPs can be used for through hole wave solder processing only. They are not intended for use in Reflow solder processing applications.

NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

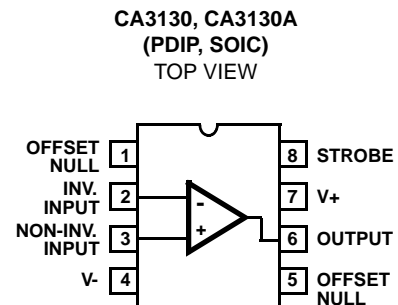
### Features

- MOSFET Input Stage Provides:
  - Very High  $Z_i = 1.5 T\Omega$  ( $1.5 \times 10^{12}\Omega$ ) (Typ)
  - Very Low  $I_i$  . . . . . 5pA (Typ) at 15V Operation  
 . . . . . = 2pA (Typ) at 5V Operation
- Ideal for Single-Supply Applications
- Common-Mode Input-Voltage Range Includes Negative Supply Rail; Input Terminals can be Swung 0.5V Below Negative Supply Rail
- CMOS Output Stage Permits Signal Swing to Either (or both) Supply Rails
- Pb-Free Plus Anneal Available (RoHS Compliant)

### Applications

- Ground-Referenced Single Supply Amplifiers
- Fast Sample-Hold Amplifiers
- Long-Duration Timers/Monostables
- High-Input-Impedance Comparators (Ideal Interface with Digital CMOS)
- High-Input-Impedance Wideband Amplifiers
- Voltage Followers (e.g. Follower for Single-Supply D/A Converter)
- Voltage Regulators (Permits Control of Output Voltage Down to 0V)
- Peak Detectors
- Single-Supply Full-Wave Precision Rectifiers
- Photo-Diode Sensor Amplifiers

### Pinout



# CA3130, CA3130A

## Absolute Maximum Ratings

DC Supply Voltage (Between V+ And V- Terminals)	16V
Differential Input Voltage	8V
DC Input Voltage	(V+ +8V) to (V- -0.5V)
Input-Terminal Current	1mA
Output Short-Circuit Duration (Note 1)	Indefinite

## Operating Conditions

Temperature Range	-50°C to 125°C
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## Thermal Information

Thermal Resistance (Typical, Note 2)	$\theta_{JA}$ (°C/W)	$\theta_{JC}$ (°C/W)
PDIP Package*	115	N/A
SOIC Package	160	N/A
Maximum Junction Temperature (Plastic Package)	150°C	
Maximum Storage Temperature Range	-65°C to 150°C	
Maximum Lead Temperature (Soldering 10s)	300°C (SOIC - Lead Tips Only)	

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**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

## NOTES:

- Short circuit may be applied to ground or to either supply.
- $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

## Electrical Specifications $T_A = 25^\circ\text{C}$ , $V_+ = 15\text{V}$ , $V_- = 0\text{V}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	CA3130			CA3130A			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
Input Offset Voltage	$ V_{IO} $	$V_S = \pm 7.5\text{V}$	-	8	15	-	2	5	mV
Input Offset Voltage Temperature Drift	$\Delta V_{IO}/\Delta T$		-	10	-	-	10	-	$\mu\text{V}/^\circ\text{C}$
Input Offset Current	$ I_{IO} $	$V_S = \pm 7.5\text{V}$	-	0.5	30	-	0.5	20	pA
Input Current	$I_I$	$V_S = \pm 7.5\text{V}$	-	5	50	-	5	30	pA
Large-Signal Voltage Gain	$A_{OL}$	$V_O = 10V_{P-P}$ $R_L = 2k\Omega$	50	320	-	50	320	-	kV/V
			94	110	-	94	110	-	dB
Common-Mode Rejection Ratio	CMRR		70	90	-	80	90	-	dB
Common-Mode Input Voltage Range	$V_{ICR}$		0	-0.5 to 12	10	0	-0.5 to 12	10	V
Power-Supply Rejection Ratio	$\Delta V_{IO}/\Delta V_S$	$V_S = \pm 7.5\text{V}$	-	32	320	-	32	150	$\mu\text{V}/\text{V}$
Maximum Output Voltage	$V_{OM+}$	$R_L = 2k\Omega$	12	13.3	-	12	13.3	-	V
	$V_{OM-}$	$R_L = 2k\Omega$	-	0.002	0.01	-	0.002	0.01	V
	$V_{OM+}$	$R_L = \infty$	14.99	15	-	14.99	15	-	V
	$V_{OM-}$	$R_L = \infty$	-	0	0.01	-	0	0.01	V
Maximum Output Current	$I_{OM+}$ (Source) at $V_O = 0\text{V}$		12	22	45	12	22	45	mA
	$I_{OM-}$ (Sink) at $V_O = 15\text{V}$		12	20	45	12	20	45	mA
Supply Current	I+	$V_O = 7.5\text{V}$ , $R_L = \infty$	-	10	15	-	10	15	mA
	I+	$V_O = 0\text{V}$ , $R_L = \infty$	-	2	3	-	2	3	mA

## CA3130, CA3130A

### Electrical Specifications Typical Values Intended Only for Design Guidance, $V_{SUPPLY} = \pm 7.5V$ , $T_A = 25^\circ C$ Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	CA3130, CA3130A	UNITS
Input Offset Voltage Adjustment Range		10k $\Omega$ Across Terminals 4 and 5 or 4 and 1	$\pm 22$	mV
Input Resistance	$R_I$		1.5	T $\Omega$
Input Capacitance	$C_I$	f = 1MHz	4.3	pF
Equivalent Input Noise Voltage	$e_N$	BW = 0.2MHz, $R_S = 1M\Omega$ (Note 3)	23	$\mu V$
Open Loop Unity Gain Crossover Frequency (For Unity Gain Stability $\geq 47pF$ Required.)	$f_T$	$C_C = 0$	15	MHz
		$C_C = 47pF$	4	MHz
Slew Rate:	SR			
Open Loop		$C_C = 0$	30	V/ $\mu s$
Closed Loop		$C_C = 56pF$	10	V/ $\mu s$
Transient Response:		$C_C = 56pF$ , $C_L = 25pF$ , $R_L = 2k\Omega$ (Voltage Follower)		
Rise Time	$t_r$		0.09	$\mu s$
Overshoot	OS		10	%
Settling Time ( $T_o < 0.1\%$ , $V_{IN} = 4V_{P-P}$ )	$t_s$		1.2	$\mu s$

NOTE:

- Although a 1M $\Omega$  source is used for this test, the equivalent input noise remains constant for values of  $R_S$  up to 10M $\Omega$ .

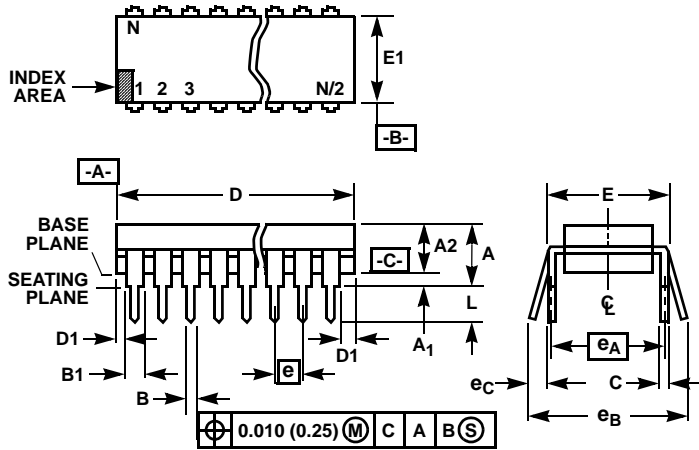
### Electrical Specifications Typical Values Intended Only for Design Guidance, $V_+ = 5V$ , $V_- = 0V$ , $T_A = 25^\circ C$ Unless Otherwise Specified (Note 4)

PARAMETER	SYMBOL	TEST CONDITIONS	CA3130	CA3130A	UNITS
Input Offset Voltage	$V_{IO}$		8	2	mV
Input Offset Current	$I_{IO}$		0.1	0.1	pA
Input Current	$I_I$		2	2	pA
Common-Mode Rejection Ratio	CMRR		80	90	dB
Large-Signal Voltage Gain	$A_{OL}$	$V_O = 4V_{P-P}$ , $R_L = 5k\Omega$	100	100	kV/V
			100	100	dB
Common-Mode Input Voltage Range	$V_{ICR}$		0 to 2.8	0 to 2.8	V
Supply Current	$I_+$	$V_O = 5V$ , $R_L = \infty$	300	300	$\mu A$
		$V_O = 2.5V$ , $R_L = \infty$	500	500	$\mu A$
Power Supply Rejection Ratio	$\Delta V_{IO}/\Delta V_+$		200	200	$\mu V/V$

NOTE:

- Operation at 5V is not recommended for temperatures below 25 $^\circ C$ .

Dual-In-Line Plastic Packages (PDIP)



NOTES:

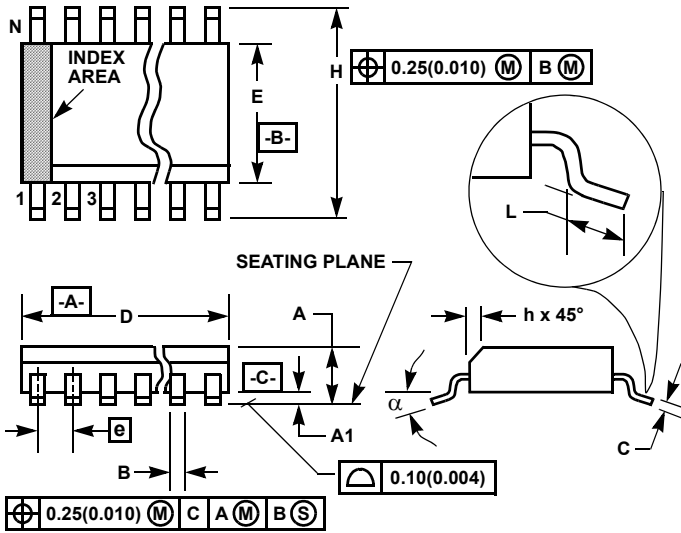
- Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
- Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
- Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
- D, D1, and E1 dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
- E and  $e_A$  are measured with the leads constrained to be perpendicular to datum  $-C-$ .
- $e_B$  and  $e_C$  are measured at the lead tips with the leads unconstrained.  $e_C$  must be zero or greater.
- B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
- N is the maximum number of terminal positions.
- Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

E8.3 (JEDEC MS-001-BA ISSUE D)  
8 LEAD DUAL-IN-LINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8, 10
C	0.008	0.014	0.204	0.355	-
D	0.355	0.400	9.01	10.16	5
D1	0.005	-	0.13	-	5
E	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
e	0.100 BSC		2.54 BSC		-
$e_A$	0.300 BSC		7.62 BSC		6
$e_B$	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	8		8		9

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Small Outline Plastic Packages (SOIC)



M8.15 (JEDEC MS-012-AA ISSUE C)  
8 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0532	0.0688	1.35	1.75	-
A1	0.0040	0.0098	0.10	0.25	-
B	0.013	0.020	0.33	0.51	9
C	0.0075	0.0098	0.19	0.25	-
D	0.1890	0.1968	4.80	5.00	3
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		-
H	0.2284	0.2440	5.80	6.20	-
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	8		8		7
$\alpha$	0°	8°	0°	8°	-

NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

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